SiHG47N60E

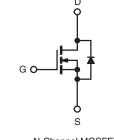




E Series Power MOSFET

PRODUCT SUMMA	RY			
V_{DS} (V) at T_J max.	650)		
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.064		
Q _g max. (nC)	220			
Q _{gs} (nC)	36			
Q _{gd} (nC)	60			
Configuration	Sing	le		





N-Channel MOSFET

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Low Figure-of-Merit (FOM) Ron x Qa
- Low Input Capacitance (Ciss)
- Reduced Switching and Conduction Losses
- Ultra Low Gate Charge (Q_q)
- Avalanche Energy Rated (UIS)
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Switch Mode Power Supplies (SMPS)
- Power Factor Correction Power Supplies (PFC)
- Lighting
 - High-Intensity Discharge (HID)
 - Fluorescent Ballast Lighting
- Industrial
 - Welding
 - Induction Heating
 - Motor Drives
 - Battery Chargers
 - Renewable Energy
 - Solar (PV Inverters)

ORDERING INFORMATION	
Package	TO-247AC
Lead (Pb)-free and Halogen-free	SiHG47N60E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_{\rm C}$	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	600	
Drain-Source Voltage Gate-Source Voltage AC (f > 1 Hz) Continuous Drain Current ($T_J = 150 \ ^{\circ}C$) V_{GS} at Pulsed Drain Current ^a Linear Derating Factor Single Pulse Avalanche Energy ^b Maximum Power Dissipation			Ň	± 20	V
Gate-Source Voltage AC (f > 1 Hz)			V _{GS}	30	
Continuous Drain Current (T. 150 °C)	V at 10.V	T _C = 25 °C T _C = 100 °C		47	
Continuous Drain Current $(1_{\rm J} = 150 {\rm C})$	V _{GS} at 10 V	T _C = 100 °C	ID	30	А
Pulsed Drain Current ^a	•		I _{DM}	145	
Linear Derating Factor				3	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	1500	mJ
Maximum Power Dissipation			PD	357	W
Operating Junction and Storage Temperature Rang	T _J , T _{stg}	- 55 to + 150	°C		
Drain-Source Voltage Slope $T_J = 125 \text{ °C}$			37)//mm	
Reverse Diode dV/dt ^d	·		dV/dt	11	V/ns
Soldering Recommendations (Peak Temperature)	10 s		300 ^c	°C	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 73.5 mH, R_q = 25 Ω , I_{AS} = 6.4 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.

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COMPLIANT

HALOGEN FREE



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PARAMETER	SYMBOL	TYP.		MAX.		UNIT				
Maximum Junction-to-Ambient	R _{thJA}	-		40			°C/W			
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.33								
		·								
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	nless otherwi	ise noted)								
PARAMETER	SYMBOL	TES		ONS	MIN.	TYP.	MAX.	UNIT		
Static						•	•			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 2	50 µA	600	-	-	V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, $I_D = 250 \ \mu A$		-	0.66	-	V/°C			
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	50 µA	2	-	4	V		
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20 V$		-	-	± 100	nA			
		V _{DS} =	= 600 V, V _{GS}	= 0 V	-	-	1			
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V,	T _J = 150 °C	-	-	10	μA		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V I _D = 24 A - 0.053 0.064		Ω						
Forward Transconductance	9 _{fs}	V _D	_S = 8 V, I _D =		-	6.8	-	S		
Dynamic			-		1		1			
Input Capacitance	C _{iss}		V _{GS} = 0 V,		-	4810	-	<u> </u>		
Output Capacitance	C _{oss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$		-	230	-	pF			
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz - 5 -								
Total Gate Charge	Qg				-	147	220			
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$ $I_D = 47 A, V_{DS} = 480 V$ - 36 -	-	nC						
Gate-Drain Charge	Q _{gd}		-	60	-					
Turn-On Delay Time	t _{d(on)}		•		-	24	50			
Rise Time	t _r	Voo	= 480 V In =	47 A	-	11	25			
Turn-Off Delay Time	t _{d(off)}	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	ns							
Fall Time	t _f									
Gate Input Resistance	R _g	f = 1	MHz, open	drain	-	0.65	-	Ω		
Drain-Source Body Diode Characteristic	S									
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	bol		-	-	47	^		
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	140	A			
Diode Forward Voltage	V _{SD}	T _J = 25 °0	C, I _S = 47 A,	$V_{GS} = 0 V$	-	-	1.2	V		
Body Diode Reverse Recovery Time	t _{rr}				-	696	-	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	$T_J = 2$	5 °C, I _F = I _S 100 A/µs, V	= 47 A,	-	16	-	μC		
Reverse Recovery Current	I _{BBM}	ai/at =	100 A/µs, V	R = ∠⊃ V	_	39	_	A		



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V_{GS} = 10

C_{gd}, C_{ds} Shorted

140 160

80 100 120

f = 1 MHz

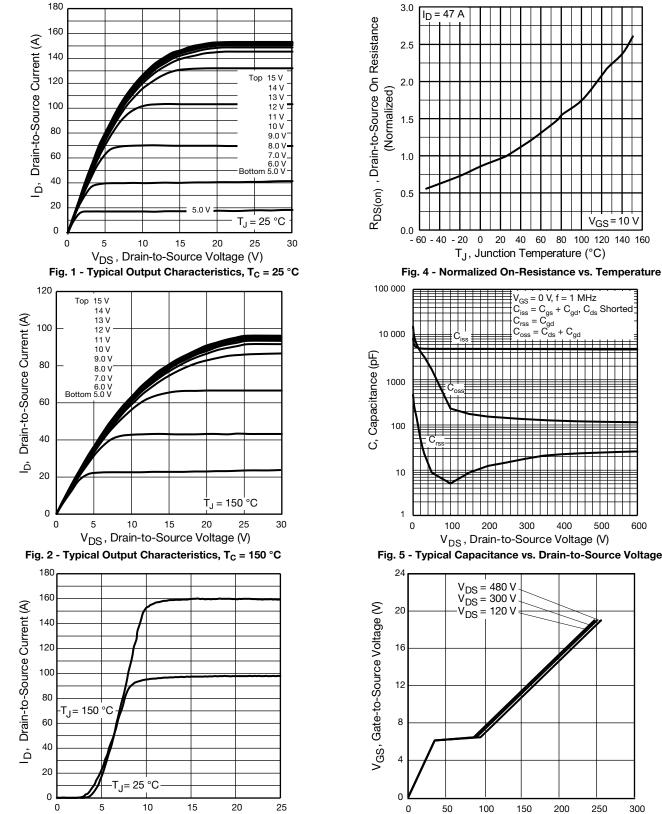
400

500

600

60





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

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V_{GS}, Gate-to-Source Voltage (V)

Fig. 3 - Typical Transfer Characteristics

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250

300

200

QG, Total Gate Charge (nC) Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage www.vishay.com

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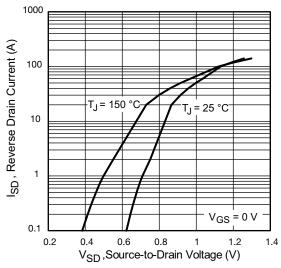
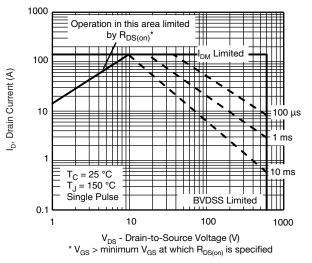
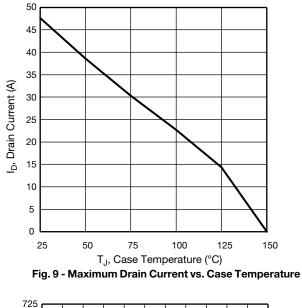


Fig. 7 - Typical Source-Drain Diode Forward Voltage







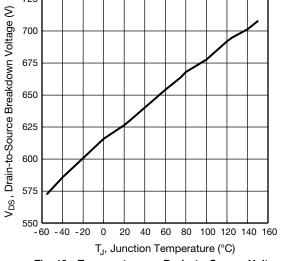
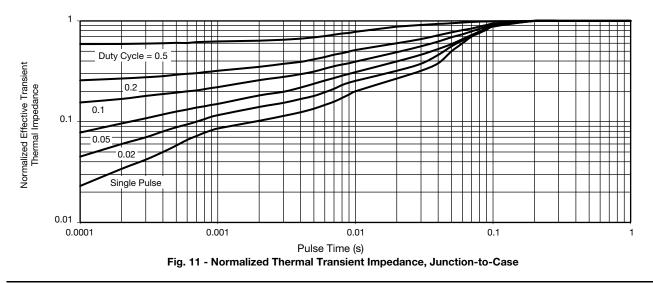


Fig. 10 - Temperature vs. Drain-to-Source Voltage



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 V_{DS} R_{D} V_{GS} D.U.T. R_{G} U T V_{DD} T V_{DD} D.U.T.

Fig. 12 - Switching Time Test Circuit

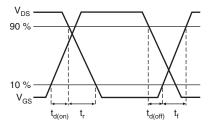


Fig. 13 - Switching Time Waveforms

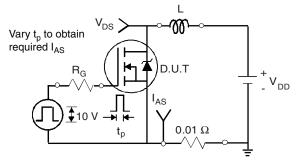
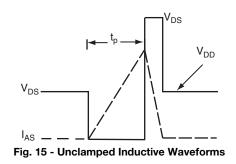


Fig. 14 - Unclamped Inductive Test Circuit



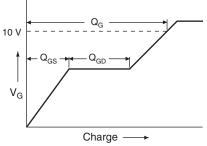


Fig. 16 - Basic Gate Charge Waveform

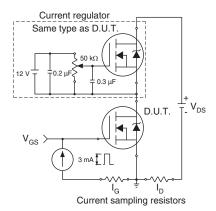


Fig. 17 - Gate Charge Test Circuit

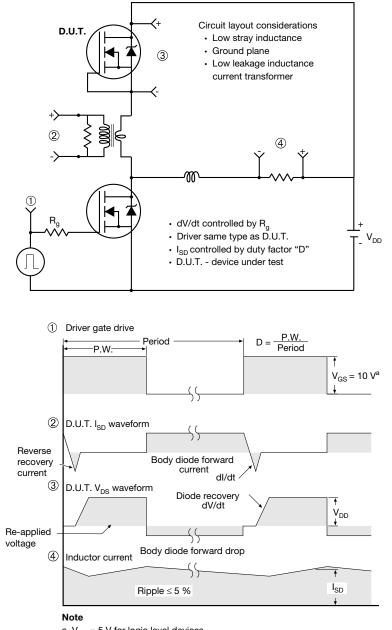
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SiHG47N60E

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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5 V$ for logic level devices

Fig. 18 - For N-Channel

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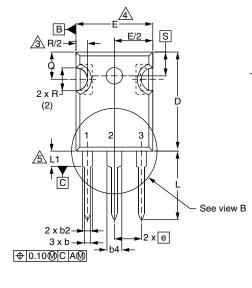
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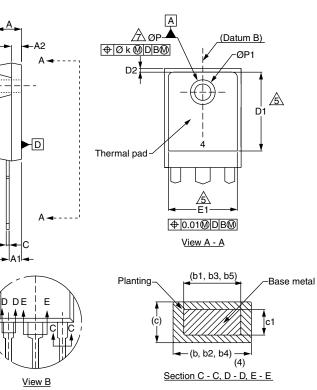


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TO-247AC (HIGH VOLTAGE)





DIM.	MILLIMETERS		INCHES			MILLIMETERS		INCI					
	MIN.	MAX.	MIN.	MAX.	DIM.	MIN.	MAX.	MIN.					
А	4.65	5.31	0.183	0.209	D2	0.51	1.30	0.020					
A1	2.21	2.59	0.087	0.102	E	15.29	15.87	0.602					
A2	1.50	2.49	0.059	0.098	E1	13.72	-	0.540					
b	0.99	1.40	0.039	0.055	е	5.46 BSC		0.215 BS					
b1	0.99	1.35	0.039	0.053	Øk	0.254		0.254		0.254		0.0)
b2	1.65	2.39	0.065	0.094	L	14.20	16.10	0.559					
b3	1.65	2.37	0.065	0.093	L1	3.71	4.29	0.146					
b4	2.59	3.43	0.102	0.135	Ν			0.300 BSC	I				
b5	2.59	3.38	0.102	0.133	ØР	3.56	3.66	0.140					
С	0.38	0.86	0.015	0.034	Ø P1	-	7.39	-					
c1	0.38	0.76	0.015	0.030	Q	5.31	5.69	0.209	I				
D	19.71	20.70	0.776	0.815	R	4.52	5.49	0.178					
D1	13.08	-	0.515	0.515 -		5.51 BSC		0.217	7				

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Contour of slot optional.

3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.

4. Thermal pad contour optional with dimensions D1 and E1.

5. Lead finish uncontrolled in L1.

6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").

7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.



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